WHAT IS CLAIMED IS:

1.An active matrix display comprising:

a pixel region formed on a substrate;

a driver circuit region formed in periphery of said pixel region to drive said pixel region, said driver circuit region being formed on said substrate;

a sealing material applied to an outer frame of said substrate; and

a liquid crystal material provided inside said sealing material;

wherein said pixel region and said driver circuit region are positioned inside said sealing material.

2. The display of claim 1 wherein said driver circuit region is in contact with said liquid crystal material.

3.The display of claim 2 wherein said liquid crystal material serves as a shock-absorbing material for said driver circuit region.

4.The display of claim 1 wherein said pixel region comprises a plurality of first thin-film transistors arranged in rows and columns, and

said driver circuit region comprises a plurality of second thin film transistors,

wherein said first and second thin film transistors are in contact with said liquid crystal material.

5.The display of claim 4 wherein said liquid crystal material serves as a shock-absorbing material for at least said second thin-film transistors.

6. The display of claim 4 wherein said first and second thin film transistors are coated with interlayer insulating

films and are in contact with said liquid crystal material via said interlayer insulating films.

7.An active matrix display comprising:

a pixel region formed on a substrate;

a driver circuit region for driving said pixel region, said driver circuit region being formed on said substrate;

a sealing material applied to said substrate;

wherein said driver circuit is incorporated in said sealing material.

8.The display of claim 7 wherein said sealing material serves as a shock-absorbing material for said driver circuit.

9. The display of claim 7 wherein said sealing material surrounds said pixel region ,and

a liquid crystal material is provided inside said sealing material.

10.An active matrix display comprising:

a pixel region formed on a substrate;

a driver circuit region for driving said pixel region, said driver circuit region being formed on said substrate;

a sealing material applied to an outer frame of said substrate;

at least one integrated circuit connected to said driver circuit;

wherein said integrated circuit is incorporated in said sealing material.

11.The display of claim 10 wherein said sealing material serves as a shock-absorbing material for said integrated circuit.

12.The display of claim 10 wherein said driver circuit is

incorporated in said sealing material.

13.The display of claim 10 wherein said integrated circuit is a microprocessor for controlling said driver circuit.

14.An active matrix display comprising:

a first substrate on which a pixel region and a driver circuit region are formed, said driver circuit region driving said pixel region;

a second substrate opposed to said first substrate ;

a sealing material applied to an outer frame of said first or second substrate;

a liquid crystal material injected between said first and second substrates and inside said sealing material;

an integrated circuit connected to said driver circuit region, said integrated circuit being incorporated in said sealing material;

wherein a space for disposing said integrated circuit is formed between said first and second substrates and said sealing material is applied in said space.

15.The display of claim 14 wherein said first substrate comprises a thinly formed portion and said space is formed between said thinly formed portion and said second substrate,

thickness of said integrated circuit being larger than a space for injecting said liquid crystal material between said first and second substrates .

16.The display of claim 14 wherein said second substrate comprises a thinly formed portion and said space is formed between said thinly formed portion and said first substrate,

thickness of said integrated circuit being larger than a space for injecting said liquid crystal material between said first and second substrates .

17.The display of claim 14 wherein said sealing material serves as a shock-absorbing material for said integrated circuit.

18.The display of claim 14 wherein said integrated circuit is a microprocessor for controlling said driver circuit.

19.The display of claim 14 wherein said driver circuit is coated with said sealing material.

20.An active matrix display comprising:

a pixel region formed on a substrate;

a driver circuit formed in periphery of said pixel region to drive said pixel region, said driver circuit being formed on said substrate;

a control circuit formed in periphery of said pixel region to drive said driver circuit, said control circuit being formed on said substrate;

a sealing material applied to an outer frame of said substrate; and

a liquid crystal material provided inside said sealing material;

wherein said pixel region, said driver circuit and said control circuit are positioned inside said sealing material, respectively.

21.The method for forming an active matrix display on a substrate comprising the steps of:

partitioning said substrate into a plurality of panel regions by a sealing material;

forming a pixel region and a driver circuit region inside each of said partitioned panel regions, said driver circuit region driving said pixel region;

dividing said substrate into a plurality of liquid crystal

panels by cutting said substrate along said sealing material; and

injecting a liquid crystal material inside each of said liquid crystal panels in order to form a plurality of liquid crystal display devices, said liquid crystal material contacting with said pixel region and driver circuit region.

22. The method of claim 21 further comprising the step of incorporating at least one integrated circuit in said sealing material.

23. The method of claim 21 wherein said pixel region comprises a plurality of first thin-film transistors arranged in a matrix form and

said driver circuit region comprises a plurality of second thin-film transistors,

wherein said first and second transistors are in contact with said liquid crystal material.

24.The method for forming an active matrix display on a substrate comprising the steps of:

partitioning said substrate into a plurality of panel regions by a sealing material;

forming a pixel region inside each of said partitioned panel regions;

incorporating a driver circuit region in said sealing material, said driver circuit region driving said pixel region;

dividing said substrate into a plurality of liquid crystal panels by cutting said substrate along said sealing material; and

injecting a liquid crystal material inside each of said liquid crystal panels in order to form a plurality of liquid crystal display devices.

25.The method of claim 24 further comprising the step of incorporating at least one integrated circuit in said sealing material.

26. The method of claim 24 wherein said pixel region comprises a plurality of first thin-film transistors arranged in a matrix form and

said driver circuit region comprises a plurality of second thin-film transistors,

wherein said first transistors are in contact with said liquid crystal material.

27.The method for forming an active matrix display comprising the steps of:

applying a sealing material to a first substrate, said first substrate being partitioned into a plurality of panel regions by said sealing material;

forming a pixel region and a driver circuit region inside each of said partitioned panel regions;

sticking said first substrate to a second substrate via said sealing material, said first and second substrates being opposed each other;

dividing said first and second substrates into a plurality of liquid crystal panels by cutting said first and second substrates along said sealing material; and

injecting a liquid crystal material inside each of said partitioned panel regions and between said first and second substrates in order to form a plurality of liquid crystal display devices ,said liquid crystal material contacting with said pixel region and driver circuit region.

28.The method of claim 27 further comprising the step of incorporating at least one integrated circuit in said sealing material.

29. The method of claim 27 wherein said pixel region comprises a plurality of first thin-film transistors arranged in a matrix form and

said driver circuit region comprises a plurality of second thin-film transistors,

wherein said first and second transistors are in contact with said liquid crystal material.